

Varistor

Material Data Sheet

Product Class:	Disk Varistor S*T6 B72214S/P*
Date	22.09.2020
IMDS ID if available	
Version:	5.01

Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Ceramic	3B	ZnO Bi2O3 Sb2O3 Co3O4 NiO others*)	91 4,0 2,5 1 0,5	1314-13-2 1304-76-3 1309-64-4 1308-06-1 1313-99-1	8,7	
Termination	Composite	4D	Cu or Ag Glass frit (boro-silicate)	95	7440-50-8 7440-22-4	0,1	
Solder	Heavy Metal	1C8	Sn Ag Cu	96,5 3 0,5	7440-31-5 7440-22-4 7440-50-8	0,9	
Leads	Heavy Metal	1C12	Cu	100	7440-50-8	6,3	
	Heavy Metal	1C8	Sn	100	7440-31-5	0,2	
Encapsulation	Duromer	2D Halogen-free coating	SiO2 Epoxy Pyromellitic dianhydride Phosphated epoxy others*)	46 40 6,5 5 2,5	60676-86-0 25036-25-3 89-32-7	3,0	
Insulating sheet	Composite	4B	Mica Adhesive	80 20	12001-26-2	0,3	
Glue	Duromer	2D	Epoxy resin Calcium carbonate Cyclamine Titanium dioxide Glycidol ether	40 24 20 10 6	61788-97-4 471-34-1 63428-84-2 13463-67-7 2224-15-9	17,5	
Ceramic shell	Ceramic	3B	SiO2 MgO Al2O3 CaO K2O Fe2O3 Na2O others*)	65,2 28,4 3,5 0,6 0,3 0,3 0,2 1,5	14808-60-7 1309-48-4 1344-28-1 1305-78-8 12136-45-7 1309-37-1 1313-59-3	63	
					Sum in total:	100	

sizes [mm]	weight range [g]	material numbers						
18 x 19 x 9	5.5 – 9.5	B72214S/P*						
Not Part of a F	Product Class							
Contact	Mr. Christoph Ronner PPD Q QM 8530 Deutschlandsberg, AUSTRIA			Important remarks: 1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not				
Division								
Address				otherwise regulated. This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are				
	Tel: +43 3462 800 2139	mailto: functional.ppd-eqpm.db@tdk-electronics.tdk.com		based on our best present knowledge and cannot be regarded as binding statement or binding product specifications, unless otherwise explicitly agreed in writing. TDK				
*) others: .(not declarable or prohibited substances acc. GADSL)				ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAÏM ANY				
**) typical mass percentage of substance				REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.				



The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (☑ valid ☐ not valid)

☑ no exemptions;
☐ Exemption 6 (a):
☐ Exemption 6 (b):
☐ Exemption 6 (c):
☐ Exemption 6 (c):
☐ Exemption 7 (a):
☐ Exemption 7 (a):
☐ Exemption 7 (c)-II:
☐ Exemption 7 (c)-II:
☐ Exemption 7 (c)-III:
☐ Exemption 8 (d):
☐ Exemption 8 (d):
☐ Exemption 9 (d):
☐ Exemption 9 (d):
☐ Exemption 9 (d):
☐ Exemption 10 (d):
☐ Exemption 10 (e)-III:
☐ Exemption 11 (e)-III:
☐ Exemption 12 (e)-III:
☐ Exemption 13 (e)-III:
☐ Exemption 14 (e)-III:
☐ Exemption 15 (e)-III:
☐ Exemption 16 (e)-III:
☐ Exemption 17 (e)-IIII:
☐ Exemption 17 (e)-IIII:
☐ Exemption 18 (e)-IIII Exemption 19 (e)-IIII Exemption 19 (e)-IIII Exemption 19 (e)-III Exemption 19 (e)-III

□ Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;

☐ Other Exemption than above